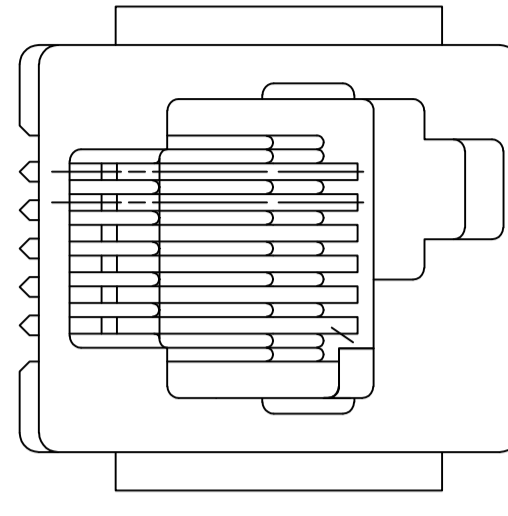
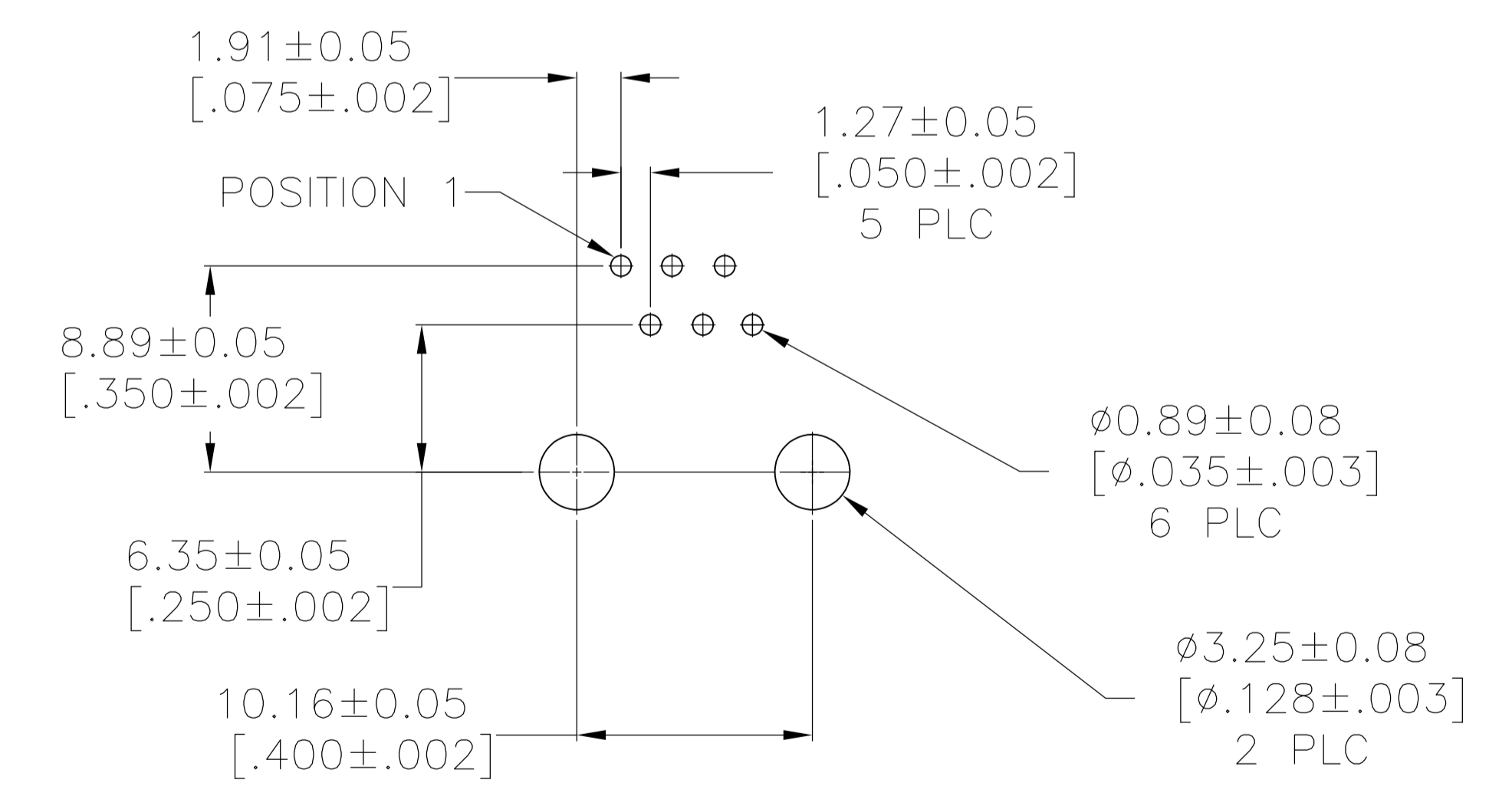
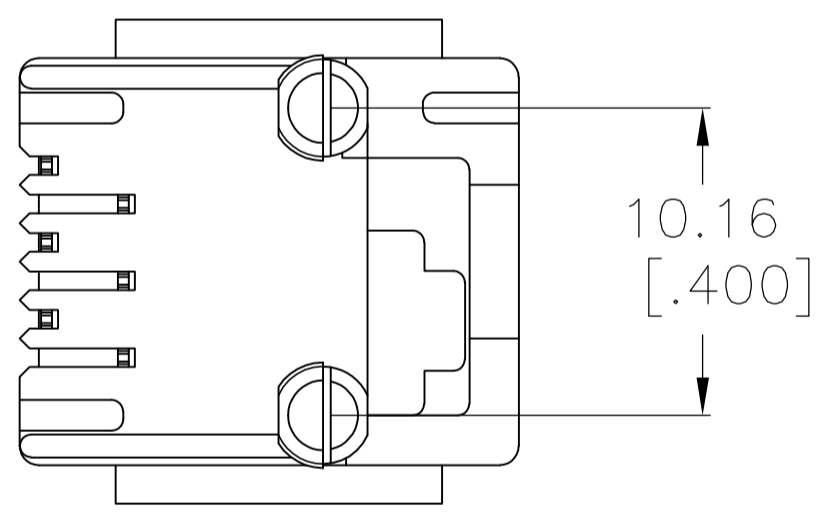
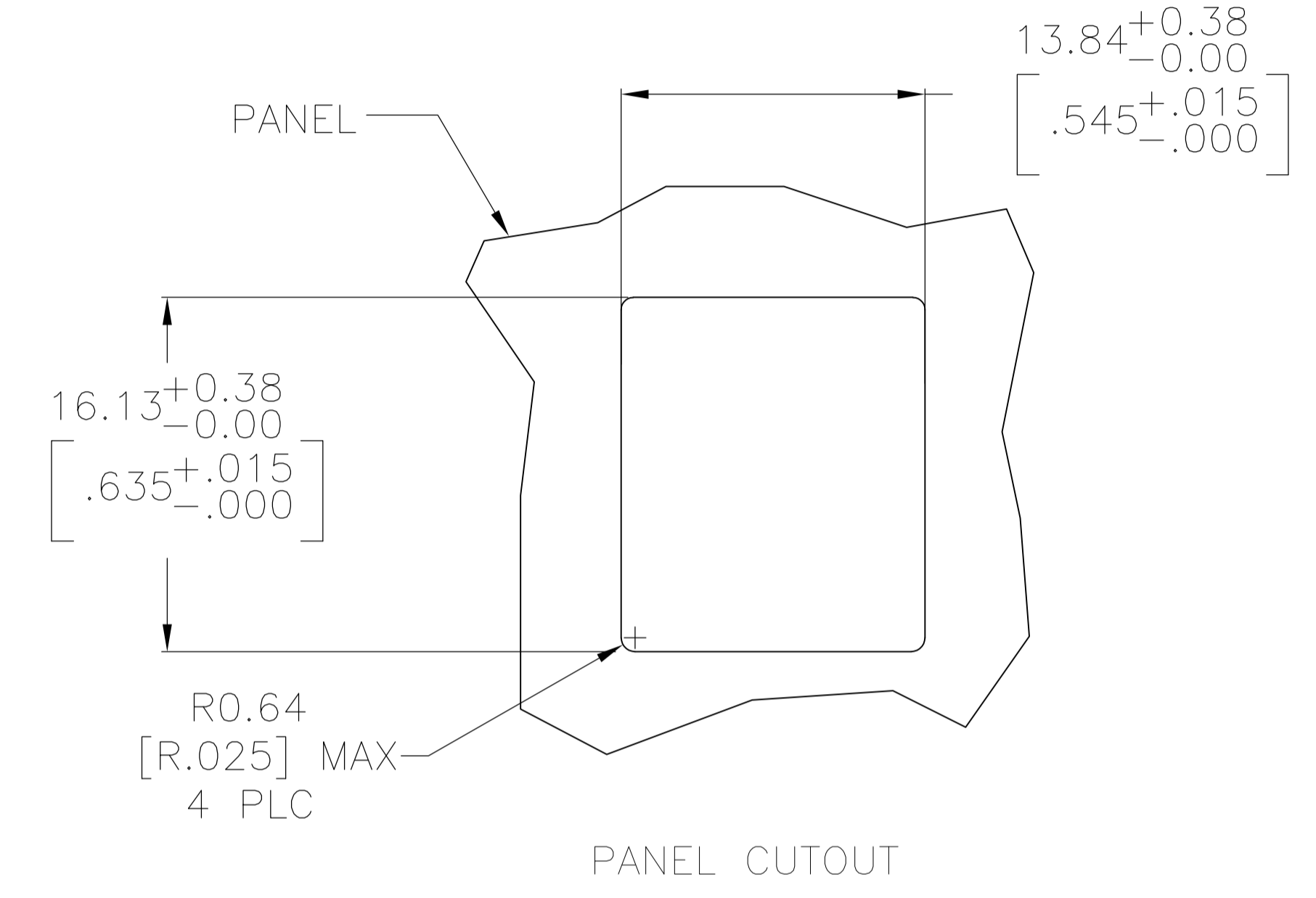
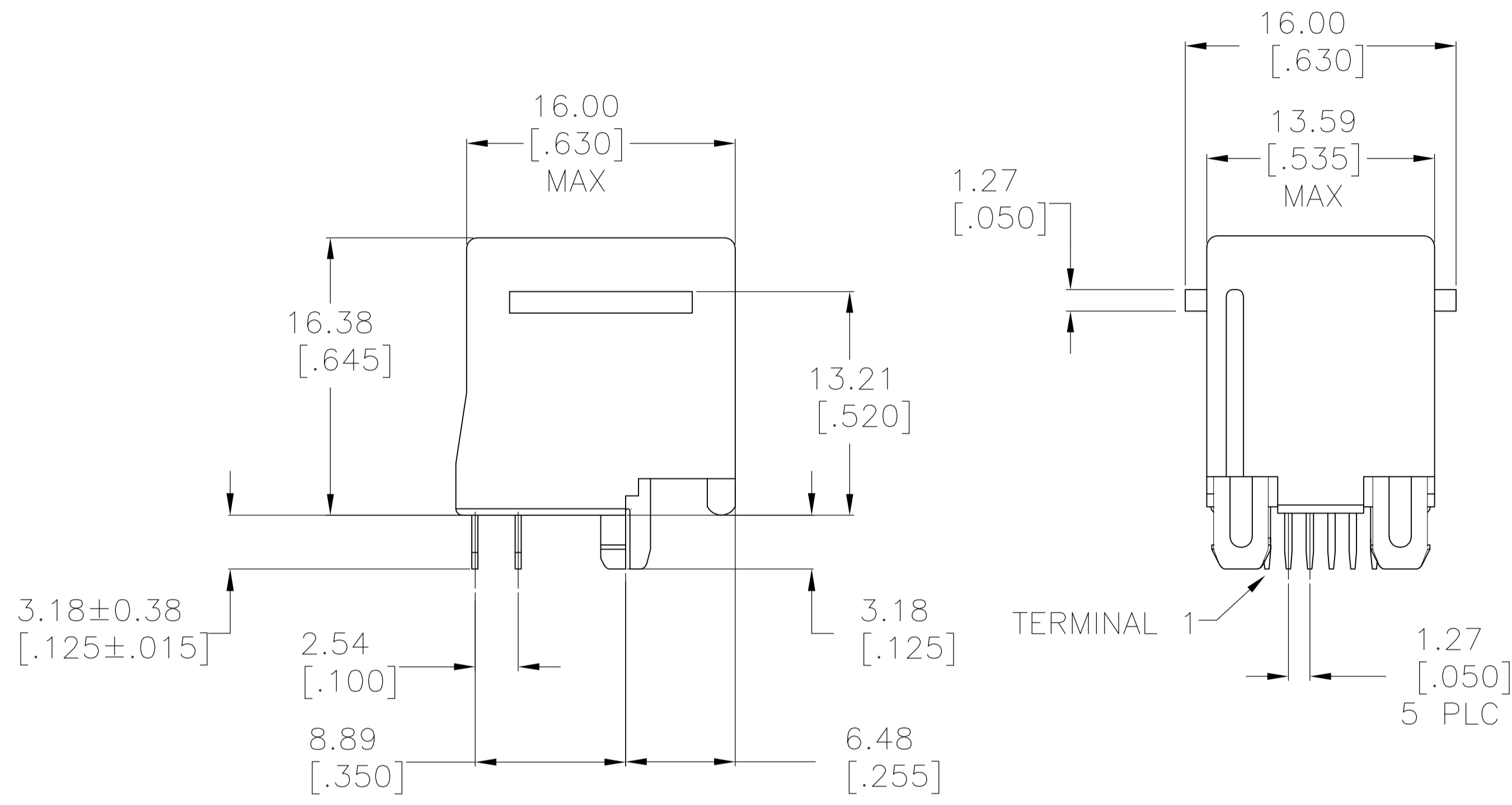


LOC		DIST		REVISIONS			
AA	00	REV	DATE	BY	CHK	APPV	
C	ECO-07-017784		10AUG07	LAM	PR		



- MATERIAL:
 HOUSING- PBT POLYESTER, GRAY.
 TERMINAL- 0.36μm[.014] THICK PHOS BRONZE
 PLATED WITH 1.27μm[.000050] MINIMUM THICK
 HARD GOLD LOCALIZED GOLD PLATE AREA AND
 3.81μm[.000150] MINIMUM THICK MATTE TIN IN
 SOLDER AREA OVER 1.27μm[.000050] MINIMUM
 THICK NICKEL UNDERPLATE.
- △ CAVITY CONFORMS TO FCC RULES AND REGULATIONS
 PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION
 FOR MODULAR TELEPHONE HARDWARE



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
 COMPONENT SIDE

5554990-1
 PART NO

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN	15AJG2007	Tyco Electronics Corporation Harrisburg, PA 17105-3608	
DIMENSIONS: mm [INCHES]		CHK	15AJG2007	NAME	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APPV	15AJG2007	MODULAR JACK ASSEMBLY, TOP ENTRY, 6 POSITION, FLANGELESS, W/ PANEL STOPS, RIGHT LATCH	
0 PLC ± -	1 PLC ± -	PRODUCT SPEC		108-1163	
2 PLC ± 0.13[.005]	3 PLC ± -	APPLICATION SPEC		114-2048	
4 PLC ± -	ANGLES ± -	SIZE		A1	
MATERIAL SEE NOTE 1	FINISH SEE NOTE 1	WEIGHT	—	SCALE	4:1
		CUSTOMER DRAWING	SCALE	SHEET	1 OF 1
		REV	—	REV C	